



**VERSION WITH MARKINGS TO SHOW CHANGES**

19. (amended once) A semiconductor chip package, comprising:  
a semiconductor chip;  
conductive leads electrically connected to and extending over a surface of the  
chip;

encapsulating material covering at least a portion of the chip and fully  
encapsulating [at least a portion of] the conductive leads; and  
electrodes each having a first portion disposed in the encapsulating material and  
contacting a conductive lead and a second portion protruding from the encapsulating  
material.

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